DGG, DGV, OR DL PACKAGE **Member of the Texas Instruments** (TOP VIEW) Widebus[™] Family • **EPIC[™]** (Enhanced-Performance Implanted NC [56 GND 1 **CMOS) Submicron Process** NC 2 55 🛛 NC **Outputs Have Equivalent 26-**Ω Series Y1 🛛 3 54 🛛 A1 **Resistors, So No External Resistors Are** GND 4 53 GND Required Y2 🛙 5 52 A2 **ESD Protection Exceeds 2000 V Per** • Y3 6 51 🛛 A3 MIL-STD-883. Method 3015: Exceeds 200 V V_{CC} [] 7 50 VCC Using Machine Model (C = 200 pF, R = 0) Y4 8 49 A4 Latch-Up Performance Exceeds 250 mA Per Y5 🛛 9 48 🛛 A5 47 🛛 A6 **JESD 17** Y6 🛛 10 **Package Options Include Plastic Shrink** • Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very **Small-Outline (DGV) Packages** description This 18-bit universal bus driver is designed for 1.65-V to 3.6-V V_{CC} operation.

Data flow from A to Y is controlled by the output-enable (\overline{OE}) input. The device operates in the transparent mode when the latch-enable (\overline{LE}) input is low. The A data is latched if the clock (CLK) input is held at a high or low logic level. If $\overline{\text{LE}}$ is high, the A data is stored in the latch/flip-flop on the low-to-high transition of CLK. When \overline{OE} is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

GND [11	46] GND
Y7 [12	45] A7
Y8 [13	44] A8
Y9 [14	43] A9
Y10 [15	42]A10
Y11 [16	41] A11
Y12 [17	40	A12
GND [18	39] GND
Y13 [19	38] A13
Y14 [20	37]A14
Y15 [21	36] A15
V _{CC} [22	35]v _{cc}
Y16 [23	34]A16
Y17 [24	33] A17
GND [25	32] GND
Y18 [26	31]A18
OE [27	30]CLK
LE (28	29	GND

NC - No internal connection

The outputs, which are designed to sink up to 12 mA, include equivalent 26- Ω resistors to reduce overshoot and undershoot.

The SN74ALVC162834 is characterized for operation from -40°C to 85°C.



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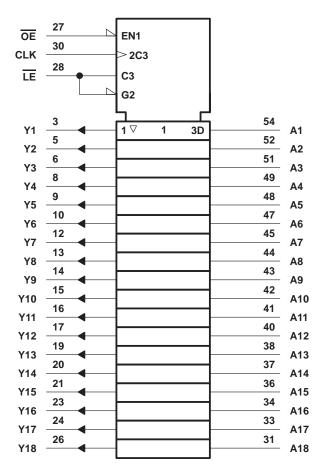
FUNCTION TABLE

	OUTPUT								
OE	LE	CLK	Α	Y					
Н	Х	Х	Х	Z					
L	L	Х	L	L					
L	L	Х	Н	н					
L	Н	\uparrow	L	L					
L	Н	\uparrow	Н	н					
L	Н	Н	Х	Y0† Y0‡					
L	Н	L	Х	Y0‡					

[†] Output level before the indicated steady-state input conditions were established, provided that CLK is high before $\overline{\text{LE}}$ goes high

[‡] Output level before the indicated steady-state input conditions were established

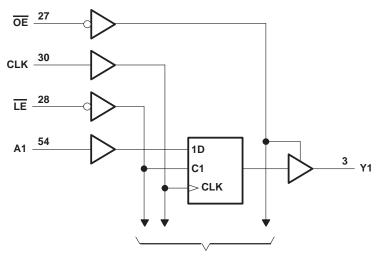
logic symbol§



§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



To 17 Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input voltage range, V_I (see Note 1) Output voltage range, V_O (see Notes 1 and 2) Input clamp current, I_{IK} ($V_I < 0$) Output clamp current, I_{OK} ($V_O < 0$) Continuous output current, I_O Continuous current through each V_{CC} or GND Package thermal impedance, θ_{JA} (see Note 3): DGG p	-0.5 V to 4.6 V -0.5 V to V _{CC} + 0.5 V -50 mA -50 mA ±50 mA ±100 mA
	kage
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 4.6 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51.



recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
VCC	Supply voltage		1.65	3.6	V
		V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$		
VIH	High-level input voltage	V_{CC} = 2.3 V to 2.7 V	1.7		V
		V _{CC} = 2.7 V to 3.6 V	2		
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	
VIL	Low-level input voltage	V_{CC} = 2.3 V to 2.7 V		0.7	V
		V _{CC} = 2.7 V to 3.6 V		0.8	
VI	Input voltage		0	VCC	V
Vo	Output voltage		0	V _{CC}	V
		V _{CC} = 1.65 V		-2	
1.	High-level output current	V _{CC} = 2.3 V		-6	
ЮН		V _{CC} = 2.7 V		-8	mA
		V _{CC} = 3 V		-12	
		V _{CC} = 1.65 V		2	
la.		V _{CC} = 2.3 V		6	mA
IOL	Low-level output current	V _{CC} = 2.7 V		8	mA
		V _{CC} = 3 V		12	
$\Delta t / \Delta v$	Input transition rise or fall rate		10	ns/V	
ТА	Operating free-air temperature	-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



PA	ARAMETER	TEST CC	ONDITIONS	Vcc	MIN	TYP†	MAX	UNIT	
		I _{OH} = -100 μA		1.65 V to 3.6 V	V _{CC} -0.	2			
		I _{OH} = -2 mA	1.65 V	1.2					
	I _{OH} = -4 mA		2.3 V	1.9					
Vон		leve 6 mA		2.3 V	1.7			V	
		$I_{OH} = -6 \text{ mA}$		3 V	2.4				
		I _{OH} = -8 mA		2.7 V	2				
		I _{OH} = -12 mA	3 V	2					
	I _{OL} = 100 μA		1.65 V to 3.6 V			0.2			
		I _{OL} = 2 mA	1.65 V			0.45			
		I _{OL} = 4 mA	2.3 V			0.4			
VOL				2.3 V			0.55	V	
		I _{OL} = 6 mA	3 V			0.55			
		I _{OL} = 8 mA		2.7 V			0.6		
		I _{OL} = 12 mA		3 V			0.8		
lj		$V_I = V_{CC}$ or GND		3.6 V			±5	μΑ	
IOZ		$V_{O} = V_{CC}$ or GND		3.6 V			±10	μΑ	
ICC		$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			40	μΑ	
∆ICC		One input at V _{CC} – 0.6 V,	Other inputs at V_{CC} or GND	3 V to 3.6 V			750	μΑ	
<u> </u>	Control inputs			3.3 V		4		ьE	
Ci	Data inputs	VI = V _{CC} or GND		3.3 V		5.5		pF	
Co	Outputs	V _O = V _{CC} or GND		3.3 V		7		pF	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

		V _{CC} =	1.8 V	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT		
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock} Clock frequency			‡		150		150		150	MHz		
	t Dulas duration	LE low		‡		3.3		3.3		3.3		ns
tw	Pulse duration	CLK high or low		‡		3.3		3.3		3.3		115
		Data before CLK↑		‡		2.1		2.1		1.7		
t _{su}	Setup time	Setup time Data before LE↑	CLK high	‡		2.3		2.3		1.9		ns
			CLK low	‡		1.9		1.9		1.5		
	Data after CLK			‡		0.6		0.6		0.7		
th	Hold time	Data after $\overline{\text{LE}}^{\uparrow}$	CLK high or low	‡		0.8		0.8		0.9		ns

[‡] This information was not available at the time of publication.



switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
		(001201)	MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
fmax			†		150		150		150		MHz
	A			†	1	5.2		5	1	4.2	
^t pd	LE	Y		†	1.3	6		6.8	1.3	5.8	ns
	CLK			†	1.4	6.8		6.1	1.4	5.4	
t _{en}	OE	Y		†	1.4	6.3		6.5	1.5	5.9	ns
^t dis	OE	Y		†	1	4.4		5.2	1.8	5	ns

[†] This information was not available at the time of publication.

switching characteristics from 0°C to 65°C, C_L = 50 pF

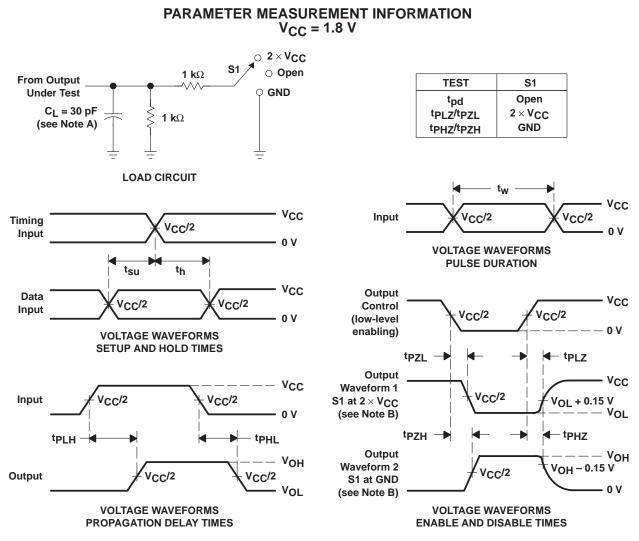
PARAMETER	FROM (INPUT)	TO	V _{CC} = ± 0.1	UNIT	
	(INPOT)	(OUTPUT)	MIN	MAX	
	A		1.4	3.9	
^t pd	LE	Y	1.8	5.5	ns
	CLK		1.8	5.2	

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		PARAMETER TEST CONDITIONS			V _{CC} = 1.8 V	V _{CC} = 2.5 V V _{CC} = 3.3 V		UNIT
	TANAMETER	FARAMETER				TYP	TYP	UNIT
	Power dissipation	Outputs enabled	- C _L = 0,	f - 10 MH 7	†	38	41	ъE
Cpd	capacitance	Outputs disabled		f = 10 MHz	†	13	15	pF

[†] This information was not available at the time of publication.



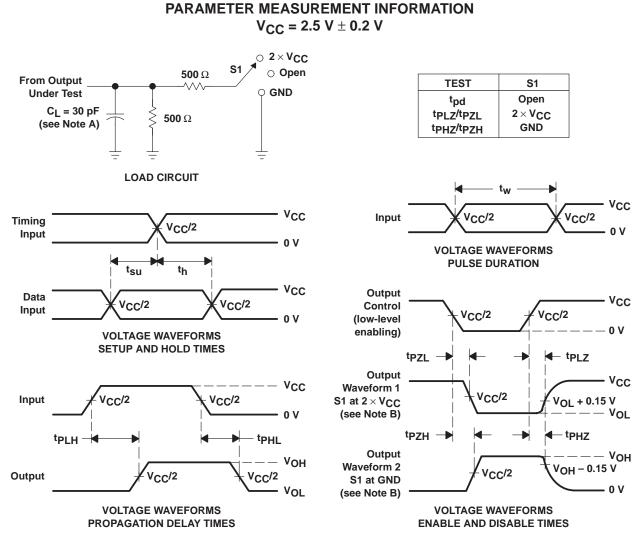


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2 ns, t_f \leq 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms





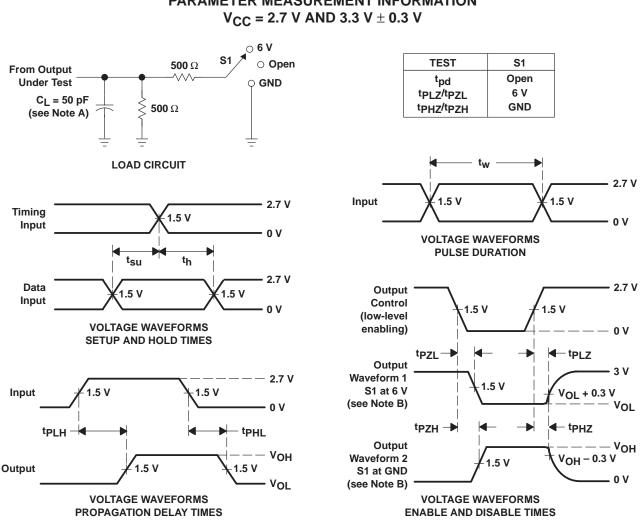
NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2 ns, t_f \leq 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.

 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. tpzL and tpzH are the same as ten.
 - G. tPLH and tPHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms





PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tPLZ and tPHZ are the same as tdis.
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 3. Load Circuit and Voltage Waveforms



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